

V-Automation, Inc.

VTR Upgrades:

- **Geneva Drive Upgrade:**
Improvement for the BEU on the VTR systems.
Replaces the belt system with a more reliable pneumatic system.
- **O₂ Analyzer:**
Replaces the current Delta F system with an analyzer that is virtually maintenance free, electrolyte free, and has a response time in seconds.
- **Segmented Profile T/C ^{patent pending} for the VTR System:**
Allows maintenance techs to change the profile T/C without the need to pull the process tube.
Interlocking ceramic pieces ^{patent pending} reduces stress on the thermocouple junction. This T/C is made to the same specifications as the OEM.
- **Spring Loaded Door Struts:**
Eliminates the Door seal problems on the CVD and Oxide systems due to changes in system alignment.
- **UPS (Battery Backup) Systems for VTR, HTR, and AVP:**
Replaces current obsolete versions of the UPS systems supplied by the OEM and helps the tools set to maintain critical data and product safety during power outage.
- **TEOS Multi-stage Filter Systems:**
This filter system provides 30% longer life than the mesh filter systems.
300,000-Angstrom deposition and Tube change at 900,000 Angstroms.
- **HEPA Filter for VTR (Teflon media):**
Filter Media E-PTFE (Boron Free)
Efficiency: 99.9995% MIN vs. MPPS at 100FPM usable Face Velocity.
Resistance: 0.48" W. G. initial avg. at 100FPM usable face velocity.
- **Process Conversion for the VTR and HTR:**
As process requirements change for the Wafer Fabs it is sometimes more beneficial to change the Process rather than the Furnace. Just ask how V-Automation, Inc. can help.

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- **Carousel/ Stocker for the VTR:**
Increases load capacity for the VTR through Automation. Better control of thin Oxide by reducing the amount of native Oxide growth through Carousels use of the N₂ loadlock. Lower particle counts and repeatable Oxide thickness targets of < 100 Angstroms accomplished.
- **Maintenance Touch Screen Terminal for the VTR:**
Designed to control and display the Digital output functions including the Digital Input functions from the rear of the VTR. Eliminates going from the gray area to cleanroom area to operate digital functions.
- **HTR / VTR Upgrade:**
V-Automation, Inc. can upgrade the HTR and VTR furnace to 8” wafer size from 6” wafer size.
- **N₂ Conservation for the VTR Load Lock Systems:**
There is no longer a need to purge your VTR Load lock systems 24/7 with N₂ to maintain a low O₂ environment.
Ask V-Automation about installing our N₂ savings package.
We can save you up to 70% of your N₂ usage per system.
- **Custom Automation and Equipment upgrade Design:**
The V-Automation engineering staffs can custom design solutions for your equipment needs.

“We are only limited by your Imagination”